

# From System KPP to Supersystem KPP

by *Gerrit Muller*      USN-SE

**e-mail:** gaudisite@gmail.com

www.gaudisite.nl

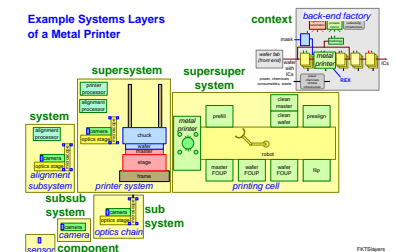
# Abstract

We will explore for your system-of-interest what its main functions are and its key performance parameters (KPP). As an architect, you should be able to explain how your key functions and KPPs serve your supersystem, as well as provide directions to the subsystems to what functionality and performance they need to deliver to your system. Combining this information with project information forms a project overview. The single sheet overview is a powerful means to keep focus in projects.

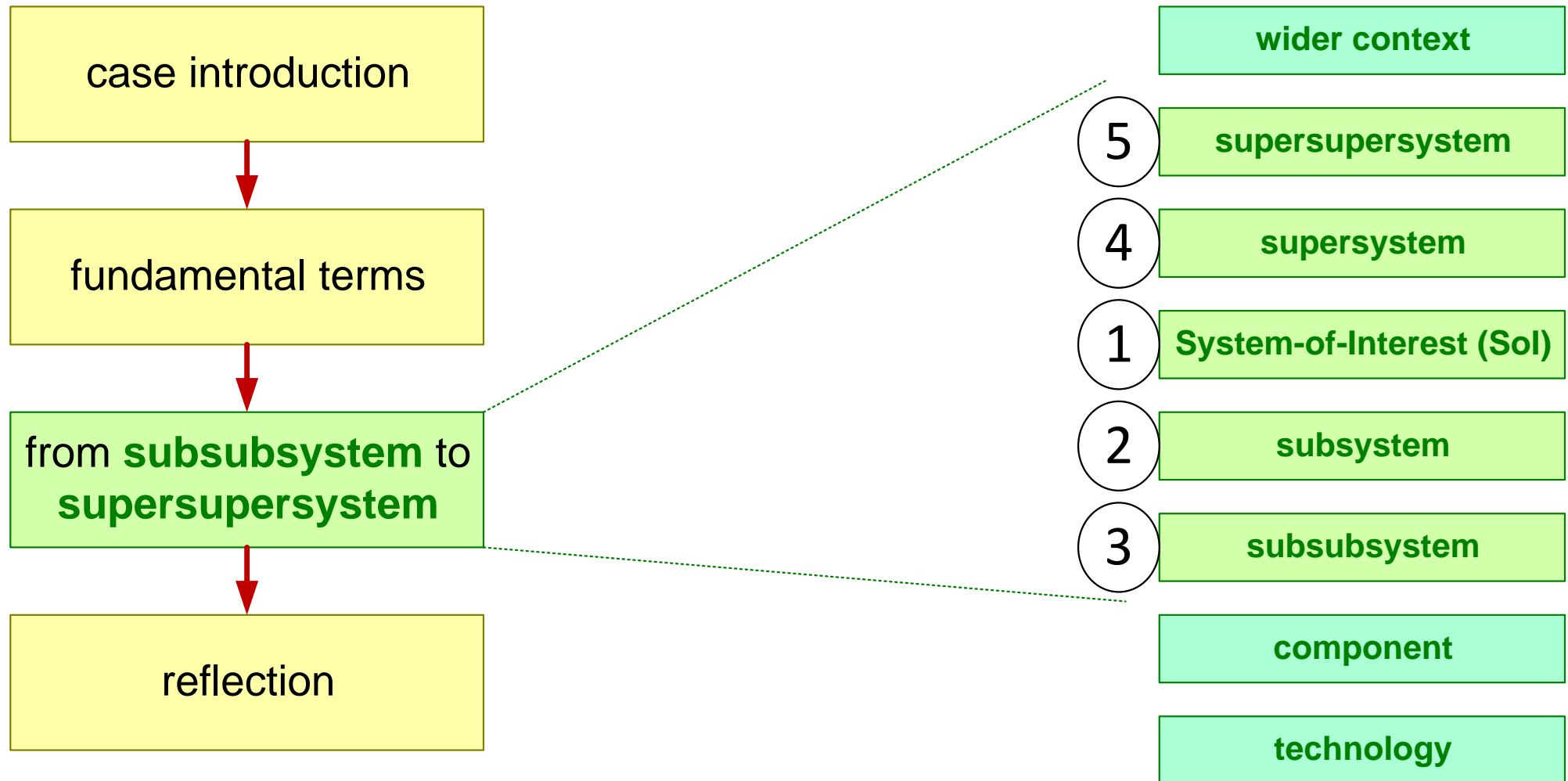
## Distribution

This article or presentation is written as part of the Gaudí project. The Gaudí project philosophy is to improve by obtaining frequent feedback. Frequent feedback is pursued by an open creation process. This document is published as intermediate or nearly mature version to get feedback. Further distribution is allowed as long as the document remains complete and unchanged.

August 24, 2025  
status: preliminary  
draft  
version: 0



# Figure of Contents™



# We Use a Case as an Example

---

Replisaurus, a **start-up** that worked on a **copper printer** for wafers, based on electrolysis technology.

**Bankrupt** in 2011 in the aftermath of the **2008 financial crisis**

Gerrit has been consulting them from 2008 until 2011

# Project Overview Metal Printer

Project overview Metal Printer R2

version 2.0. January 22, 2023  
author: Gerrit Muller

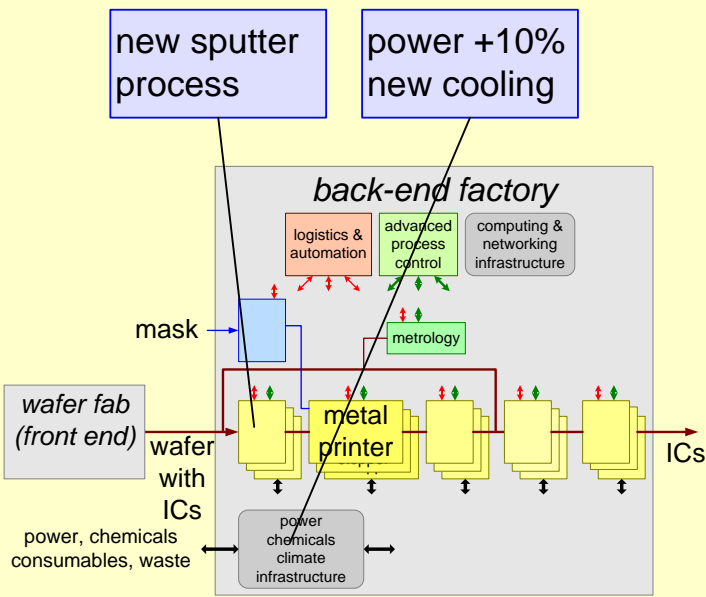
### Project Goals

support production of node 1C  
process development Q2 2022  
volume production Q2 2023  
productivity 30,000 W/m  
yield 95%

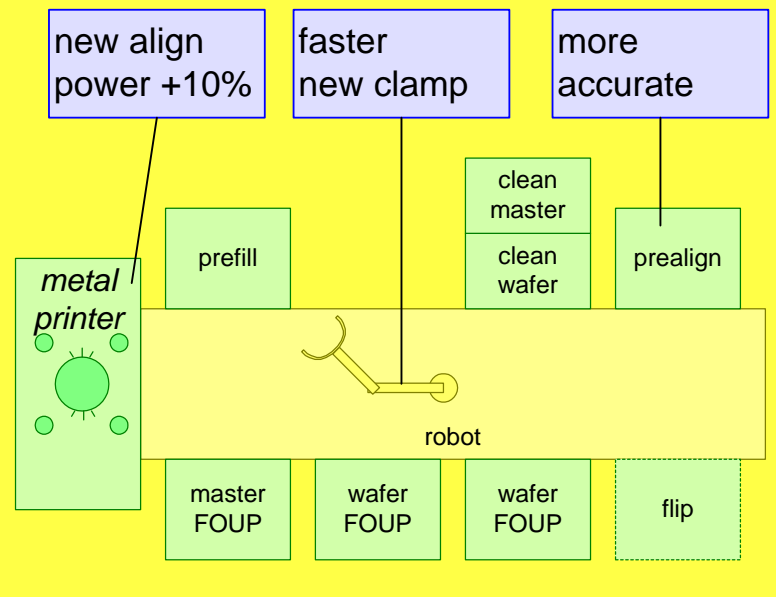
### Key Performance Parameters

min. line width 100 nm  
overlay 30 nm  
throughput 100 WPH  
MTBF 2000 hr  
wafer size 300 mm  
power 5 kW  
clean room class C  
floor vibration class D

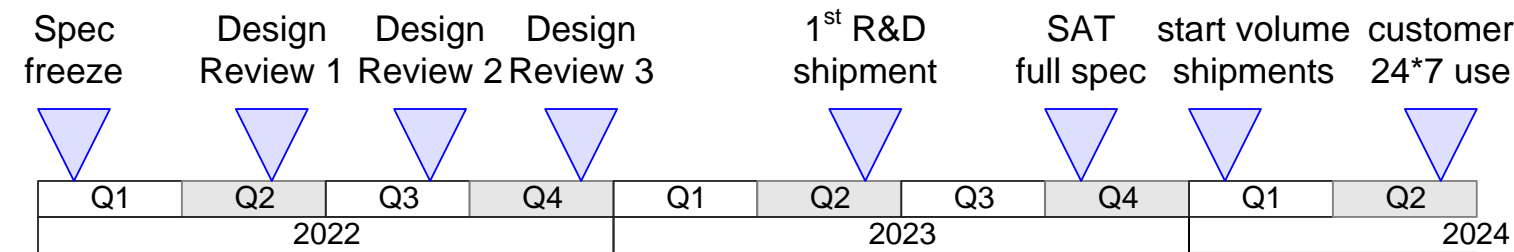
### system context



### system of interest



### project master plan

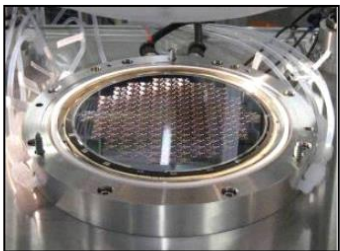
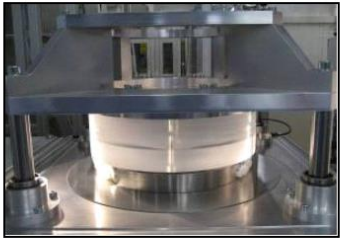


### changing enabling systems

conditioned transport  
calibration wafers  
calibration metrology

## 200mm ECPR tools

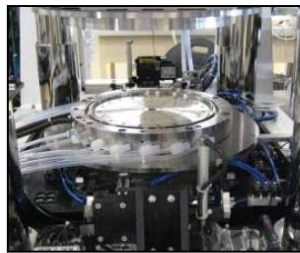
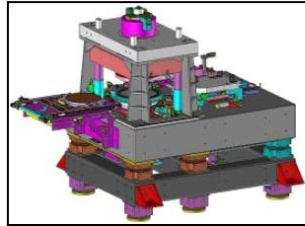
2006  
R&D 1.0



200mm hydraulic non-aligned tool for chamber & process development

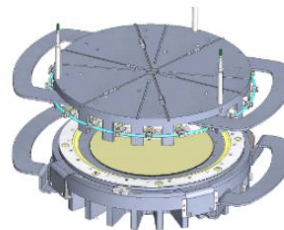
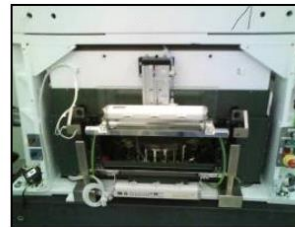
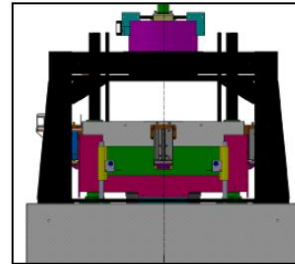
## 300mm ECPR tools. Can be configured with 200 or 300mm kits.

2007  
REX 1.0



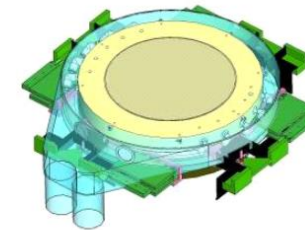
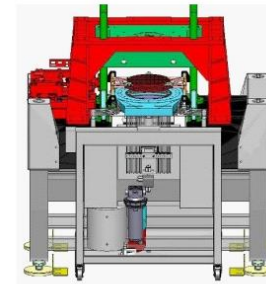
First aligned ECPR dev. tool. 200/300mm compatible.

2008  
R&D 2.0



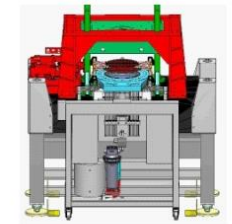
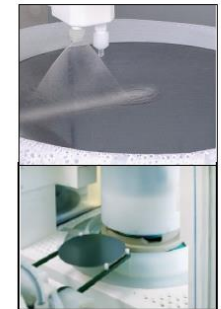
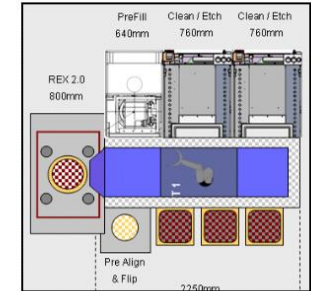
Integrated ECPR control. Non-aligned, Footprint, confinement

2009  
REX 2.0



Production oriented print module. Cycle time, overlay, confinement & footprint focus.

2010  
Alpha 1.0



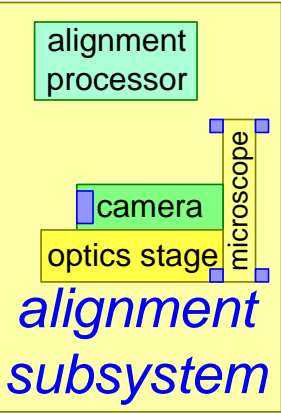
First integrated tool prefill - clean - print - seed etch.

courtesy Replisaurus

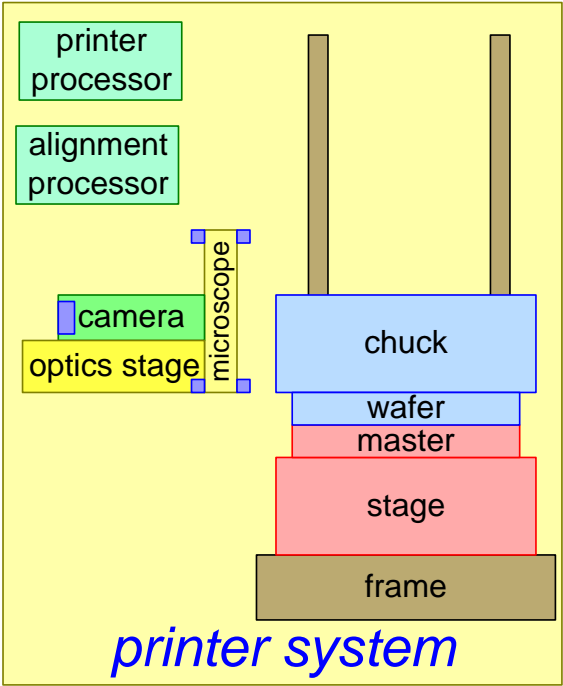
## Case: Metal Printer

# Example Systems Layers of a Metal Printer

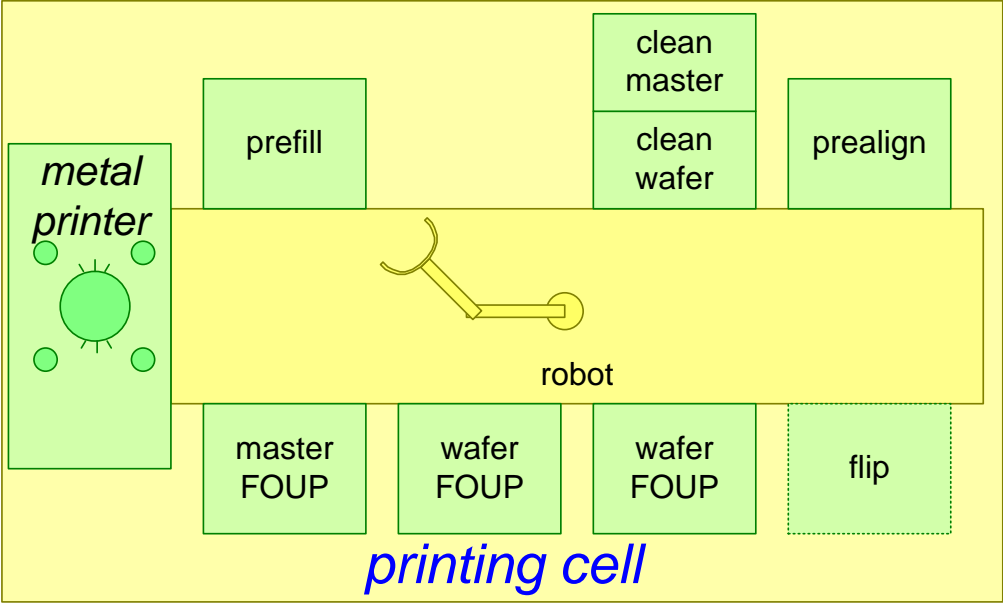
system



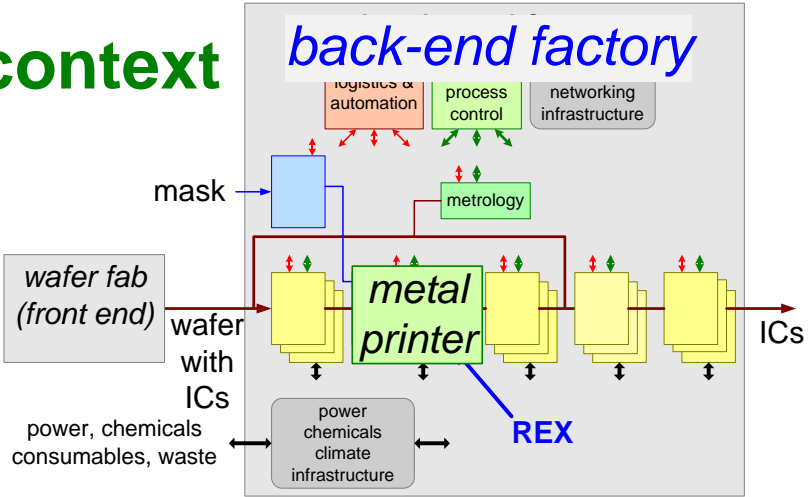
supersystem



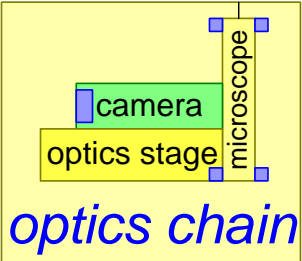
supersuper system



context



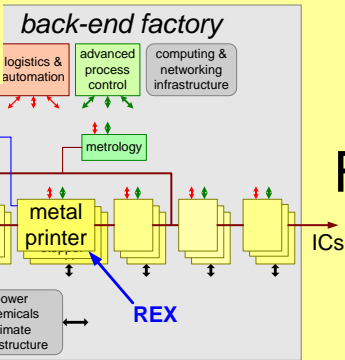
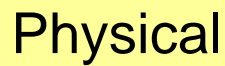
subsub system



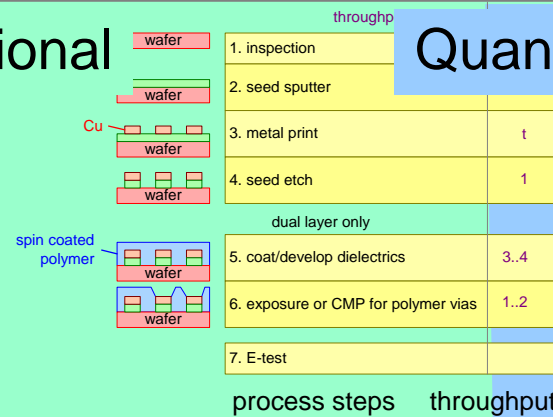
sub system

sensor component

## Metal Printer: 3 Levels of Systems on 1 A3 (all numbers have been removed for competitive sensitivity) CTEAmetalPrinterA3



*back-end factory: systems and process model*



process steps    throughput

## Quantified

Gerrit Muller

0.1

scope

status

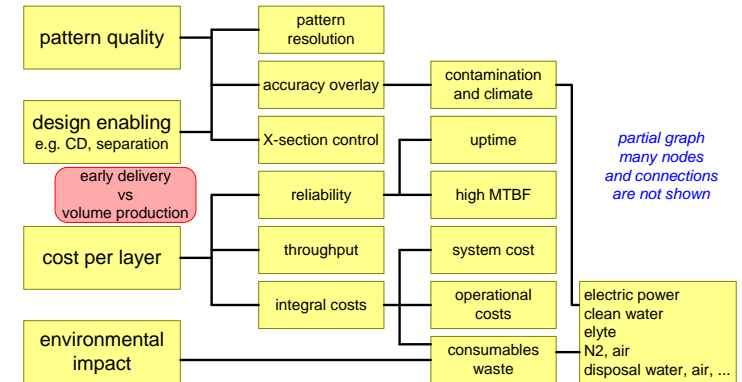
system and supersystem

preliminary draft

t update

August 3, 2010

### Document meta-information



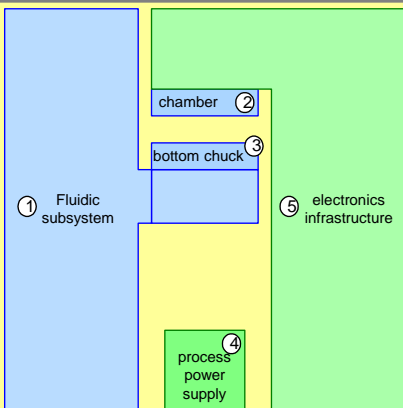
*partial graph  
many nodes  
and connections  
are not shown*

customer key drivers

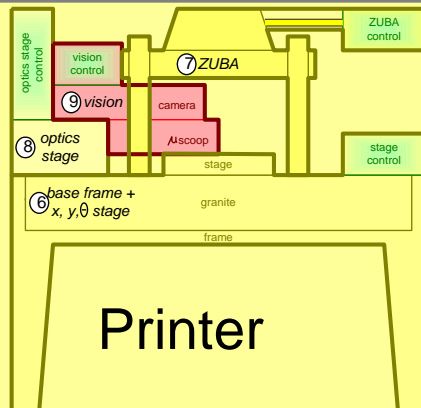
min. line width	a $\mu\text{m}$	wafer size	200, 300 mm
overlay	b $\mu\text{m}$	power	x kW
throughput	c WPH	clean room class	
MTBF	d hr	floor vibration class	

key performance parameters

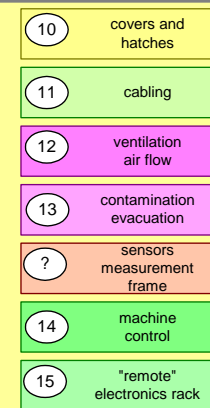
### Customer key-drivers and Key Performance Parameters



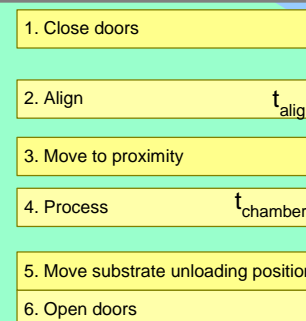
metal printer back side



metal printer front side



integrating  
subsystems



metal printer  
functional flow

$$t_{\text{print}} = t_{\text{p,prepare}} + t_{\text{p,align}} + t_{\text{chamber}}(\text{thickness}) + t_{\text{p,finalize}}$$

$$t_{\text{prepare}} = t_{\text{close doors}} + t_{\text{move to proximity}}$$

$$t_{\text{finalize}} = t_{\text{move to unload}} + t_{\text{open doors}}$$

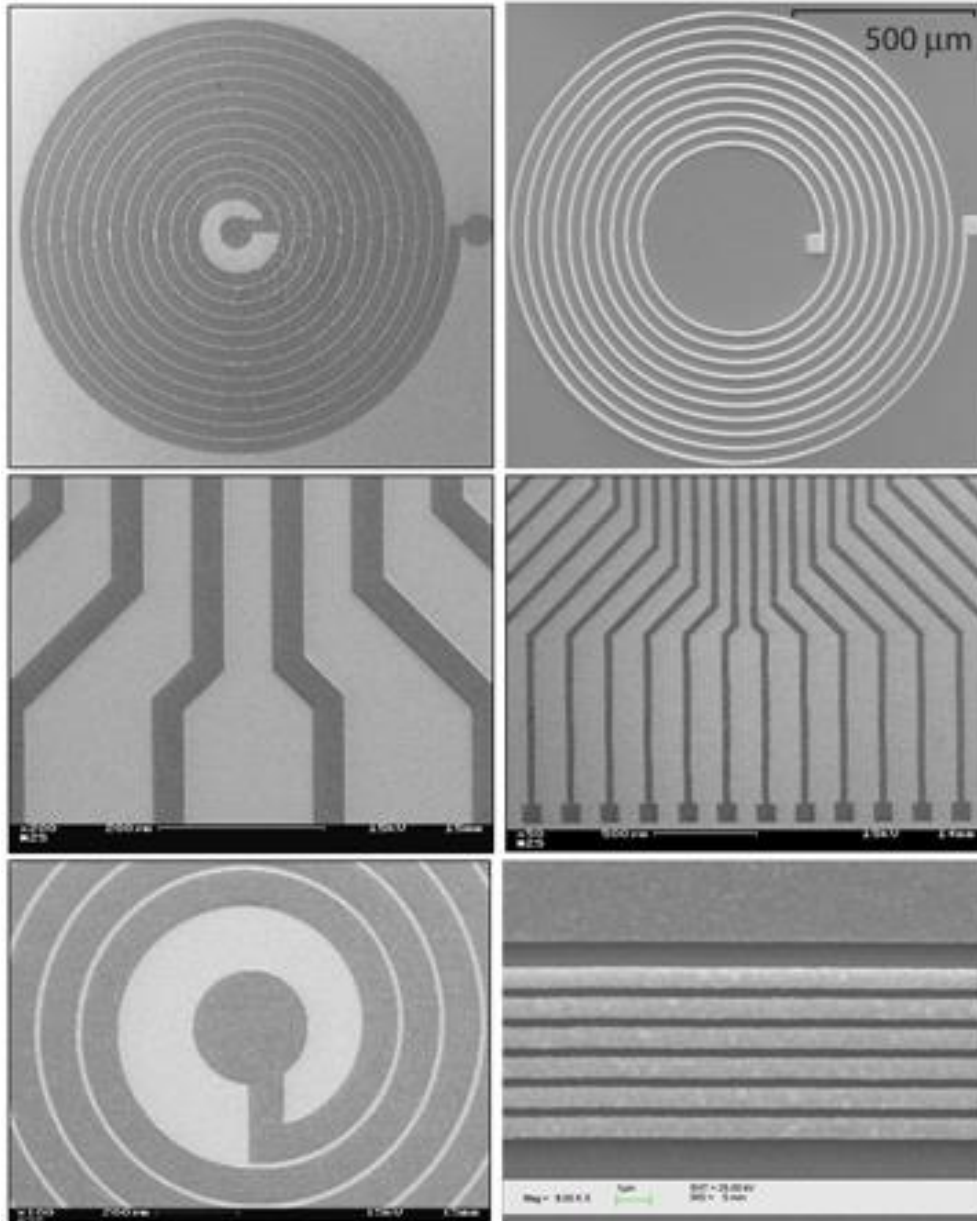
$$t_{\text{print}} = t_{\text{p, overhead}} + C_{\text{transfer}} * \text{thickness}$$

*note: original diagram was annotated with actual performance figures for confidentiality reasons these numbers have been removed*

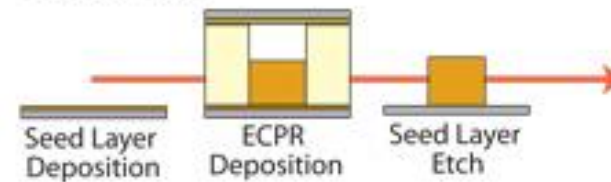
formula print cycle time

### metal printer subsystems, functions, and cycle time model

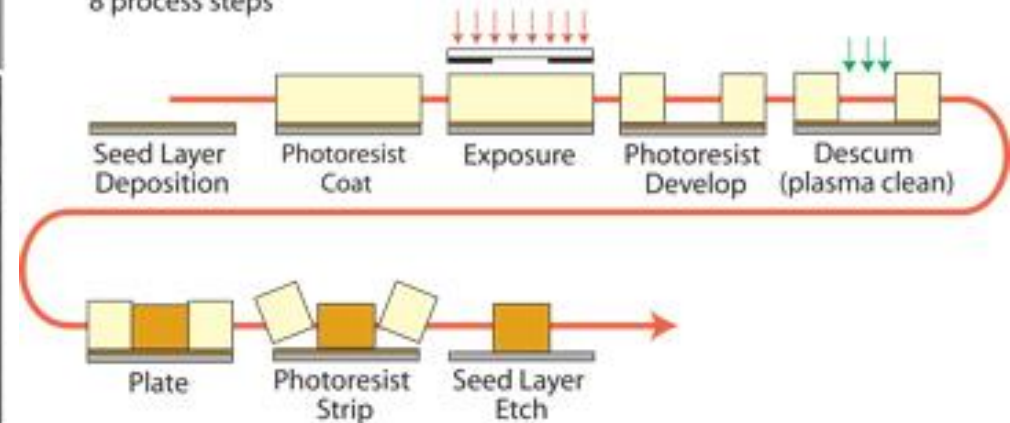
# Application of the OEM System



## ECPR - ElectroChemical Pattern Replication 3 process steps

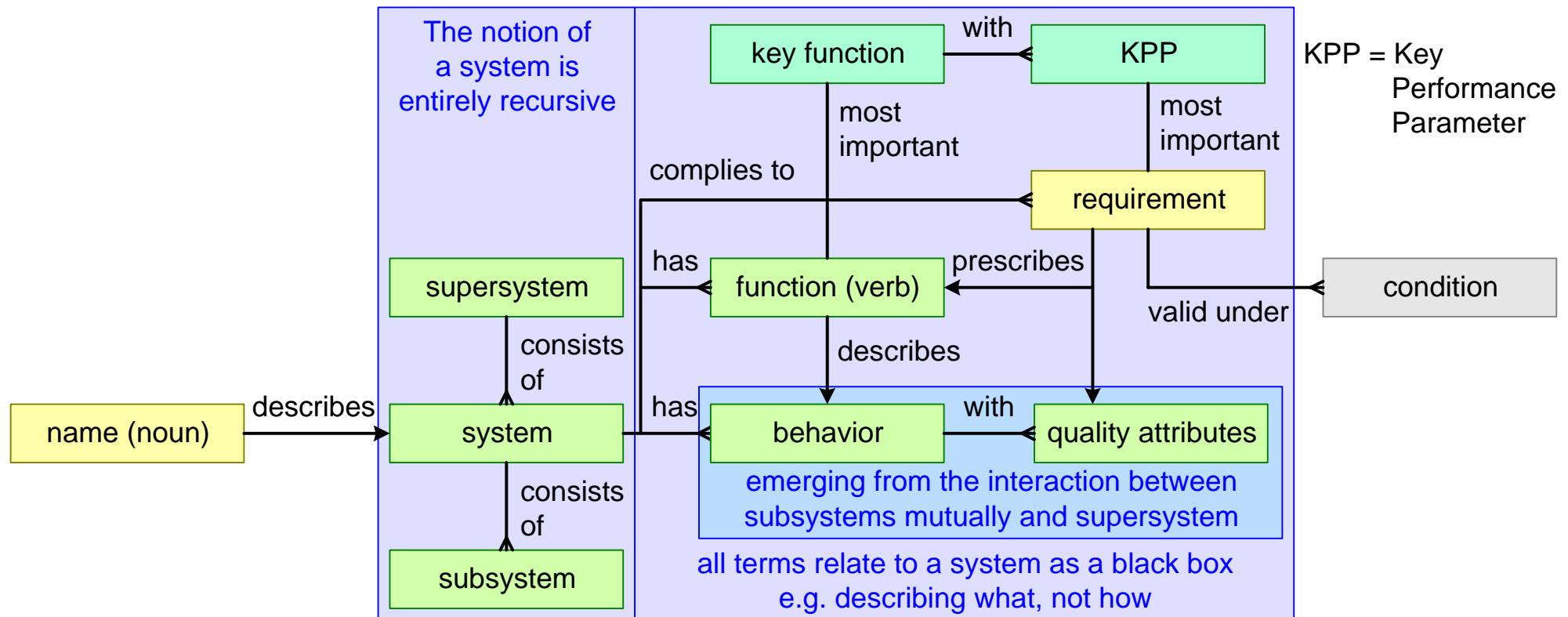


## Conventional lithography based metallization 8 process steps

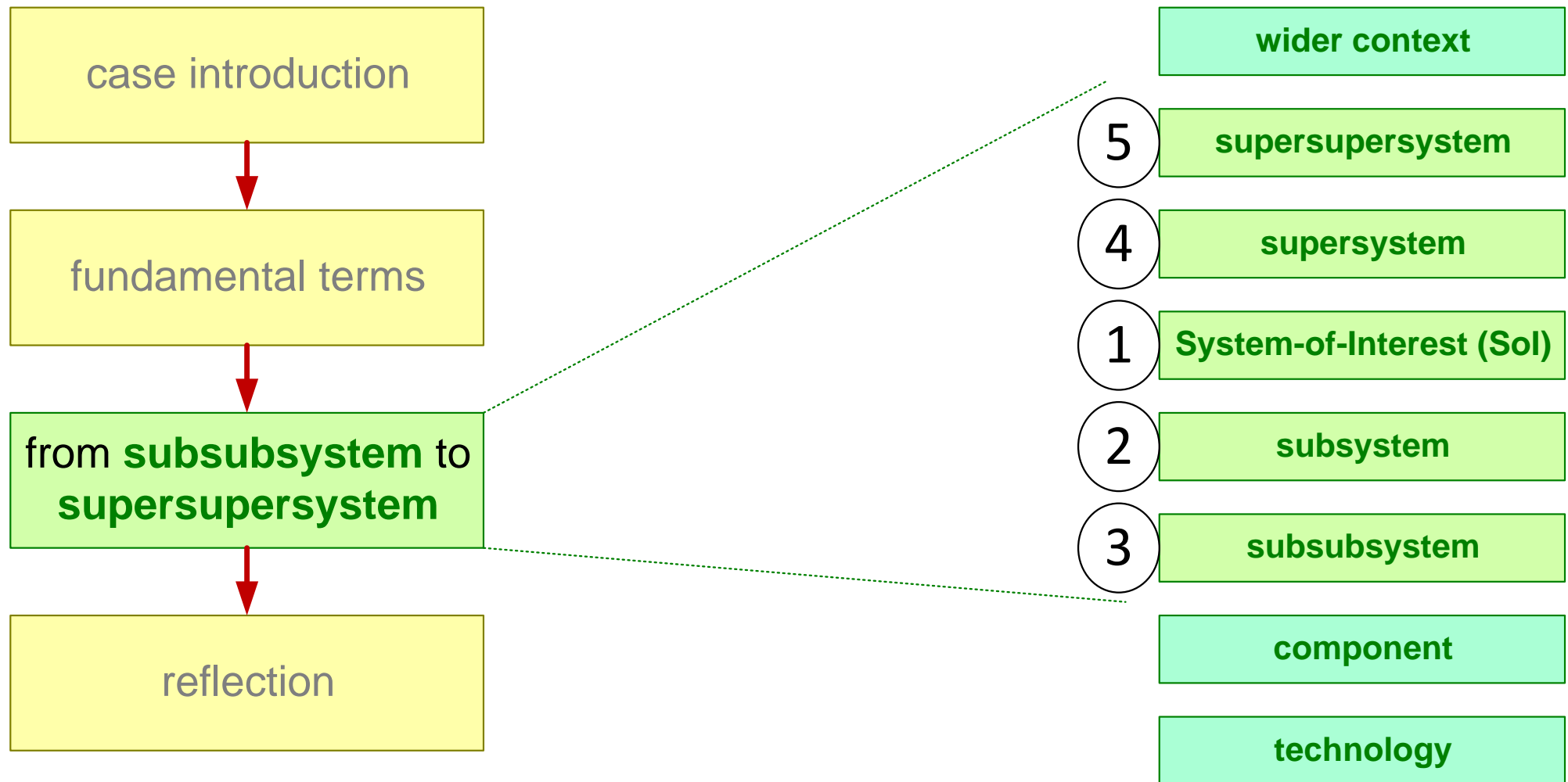


A metal printer  
replaces 6 process step by 1 process step.  
It prints an entire wafer at once.

# Systems Engineering Theory: Relevant Terms



# Time to Work and to Be Active



# What is your System-of-Interest?

---

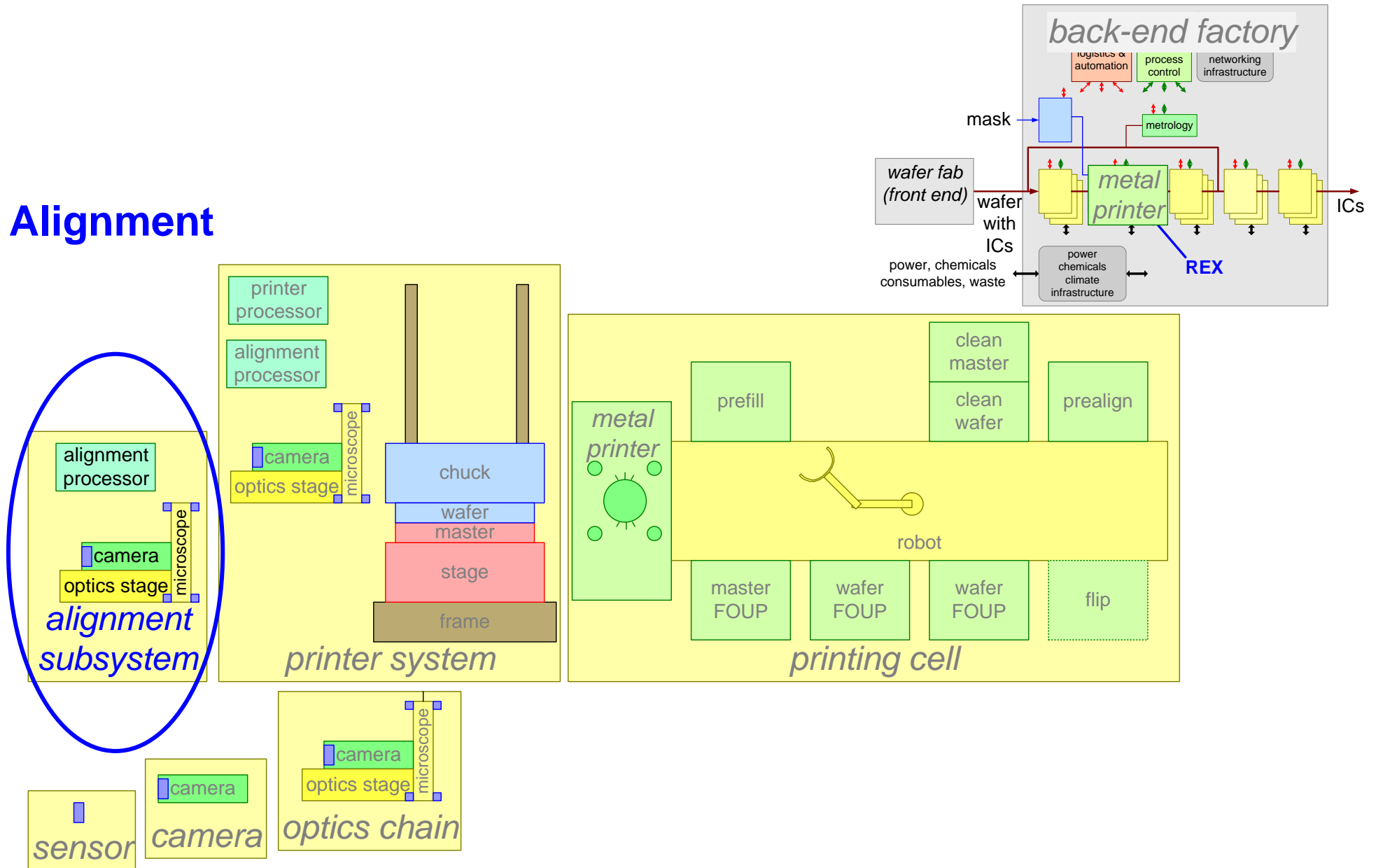
Please go to

<link to a shared spreadsheet on ASML intranet>

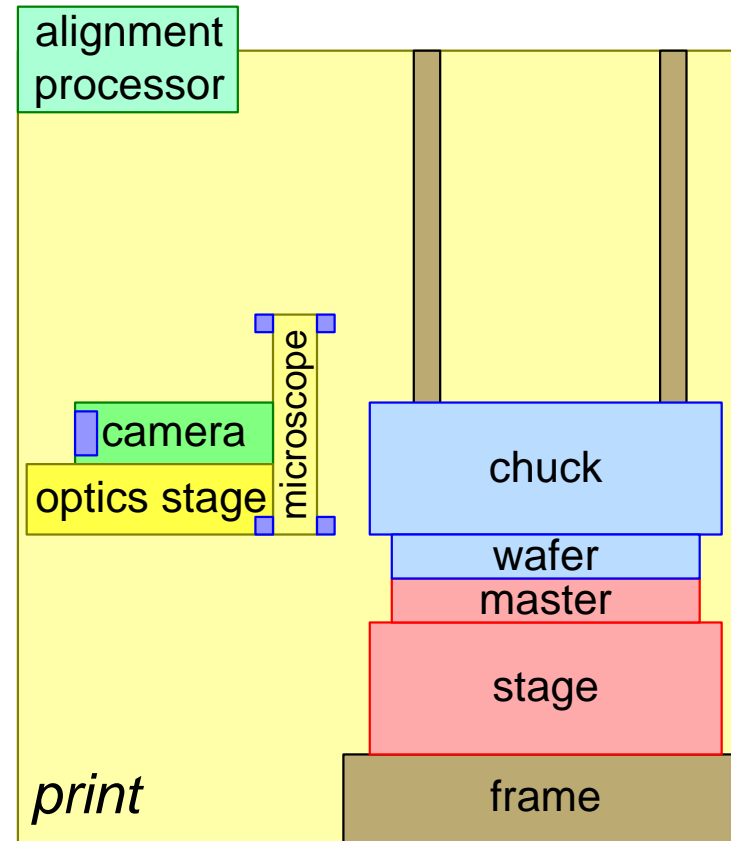
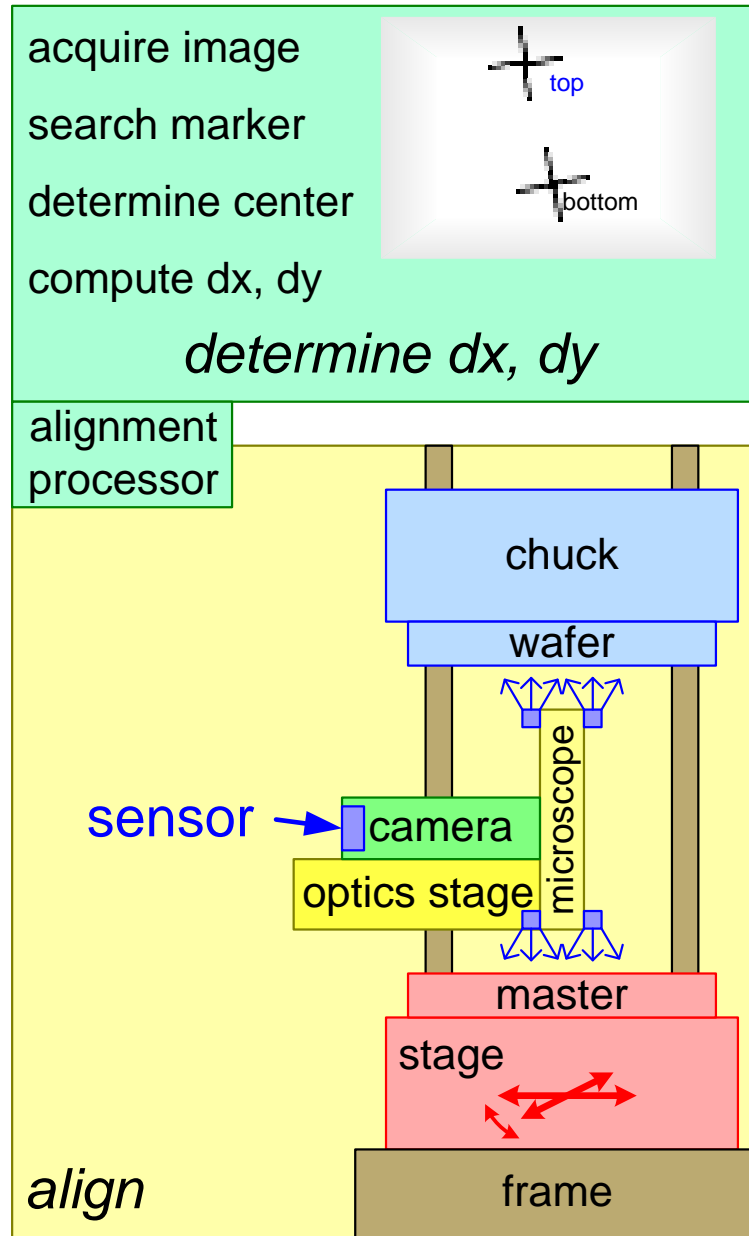
- Go to the row with your seat number
- Fill in your name (column B)
- What is your System-of-Interest (Column C)

# The System-of-Interest: Alignment

## Alignment



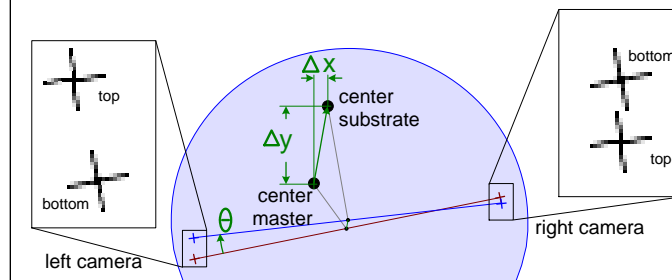
# Basics of Alignment Function



## KPPs

overlay	1 $\mu\text{m}$
$t_{\text{align}}$	10 s
$t_{\text{calibrate}}$	5 min.
Search field	20 * 20 mm
marker field	1 mm

## alignment algorithm

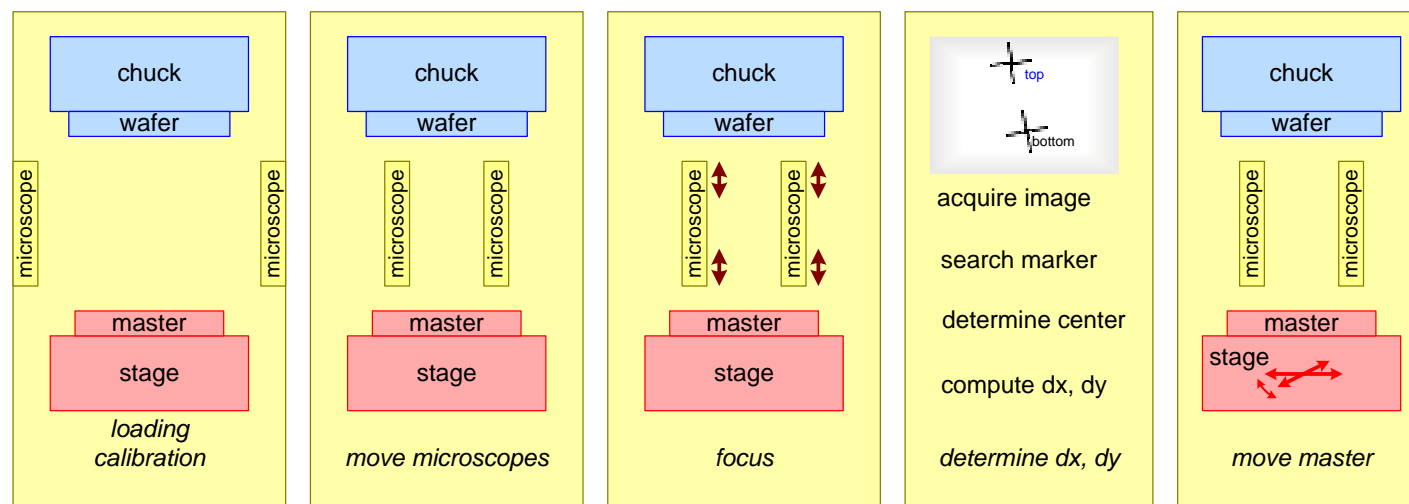


## workflow

requires microscopes to be  $\varphi_x$  and  $\varphi_y$  corrected

1. move microscopes to markers
2. focus master by lens movement
3. focus substrate by lens movement
4. acquire images
5. find markers
6. compute marker centers
7. compute wafer centers and  $\theta$
8. move master  $\Delta x, \Delta y, \theta$
9. repeat 4..8 to verify alignment
10. remove microscopes

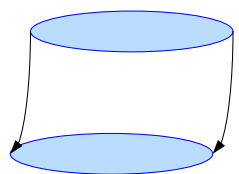
assumes marker position to be known coarsely and markers to be within microscope FOV



## alignment challenge

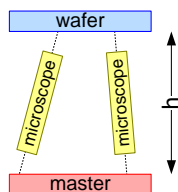
1<sup>st</sup> order

ZuBa move imperfect  
Microscope not perfectly vertical



vertical move causes some translation and rotation causing

$(dx, dy)_{\text{left}}$   $(dx, dy)_{\text{right}}$



imperfect vertical axis causes dx, dy offsets

$$dx = \varphi_x * h$$

## physical diagram



measurement accuracy determines required resolution

camera

#pixels  $\approx$  5M  
pixel resolution versus maximum Field of View read-out and processing time

optical resolution magnification

DoF  $\updownarrow$

microscope

wafer

displacement determines required Field of View

# What are the Key Functions and KPPs of your Sol?

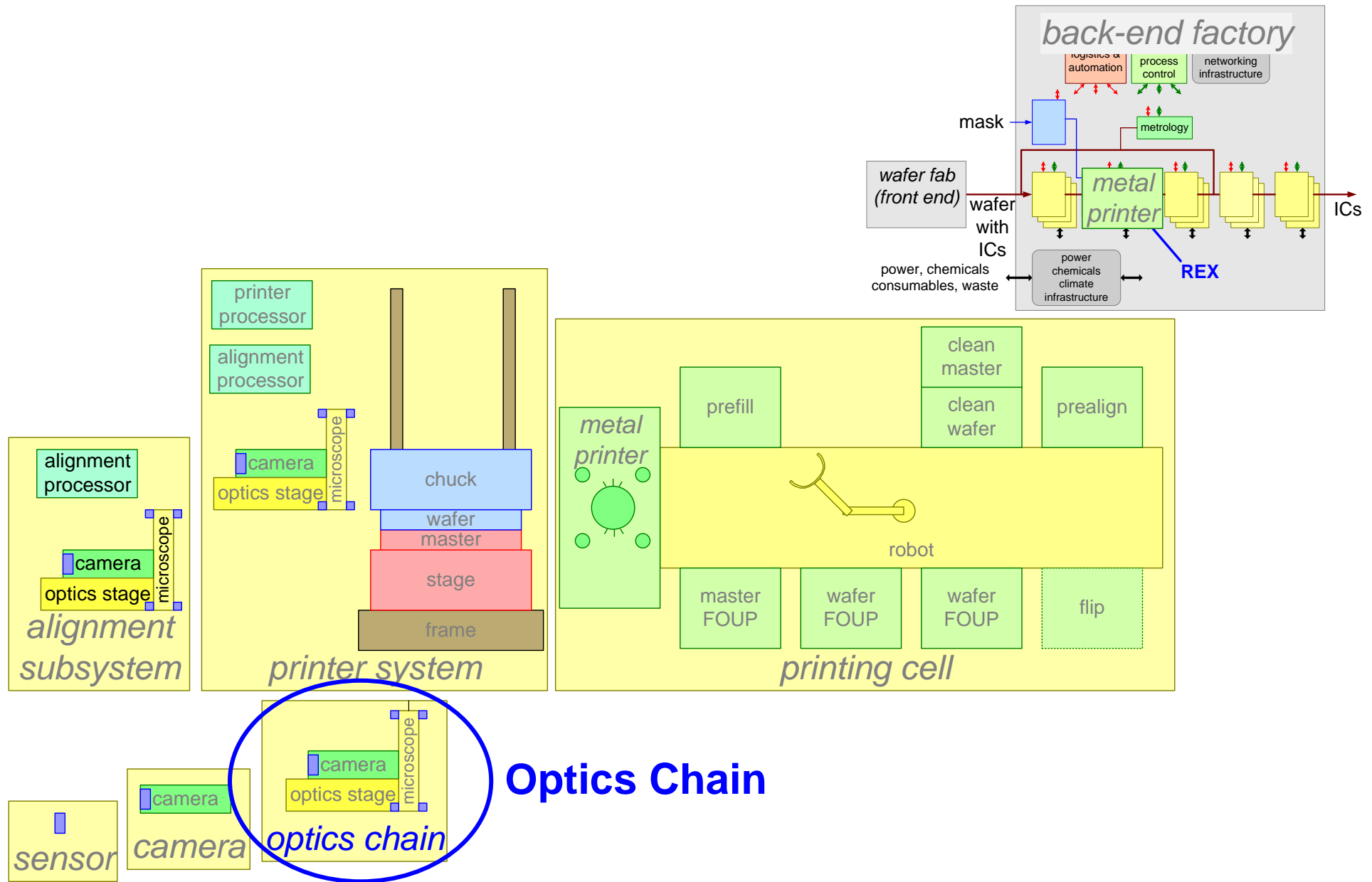
---

- Name 3 key functions of your Sol
- Name 3 KPPs of your Sol
- Quantify these KPPs
- How confident are you about your Sol answers?

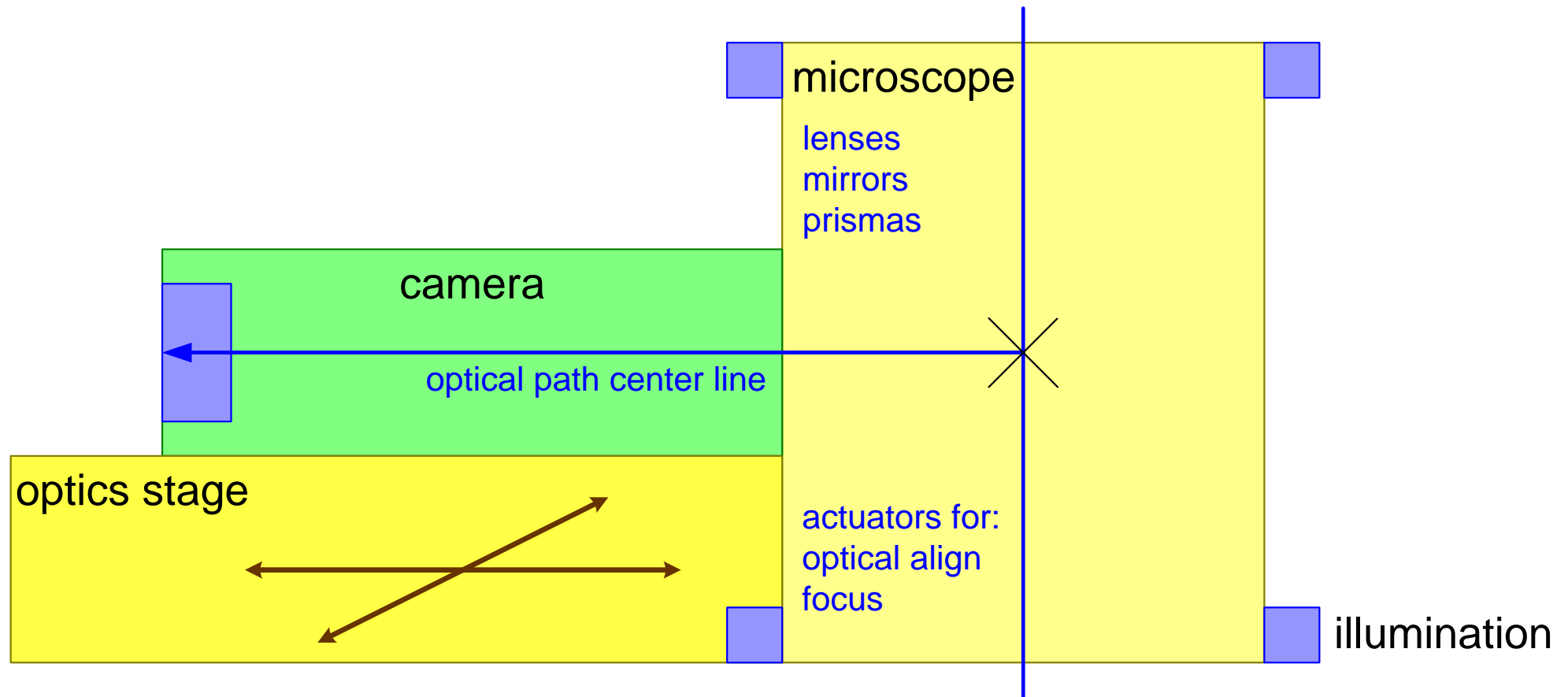
Possible  
*Key Performance Parameters*  
of the alignment subsystem

- dx, dy after alignment
- alignment cycle time
- robustness for markers, patterns, wafers, temperature
- cost, weight, size subsystem

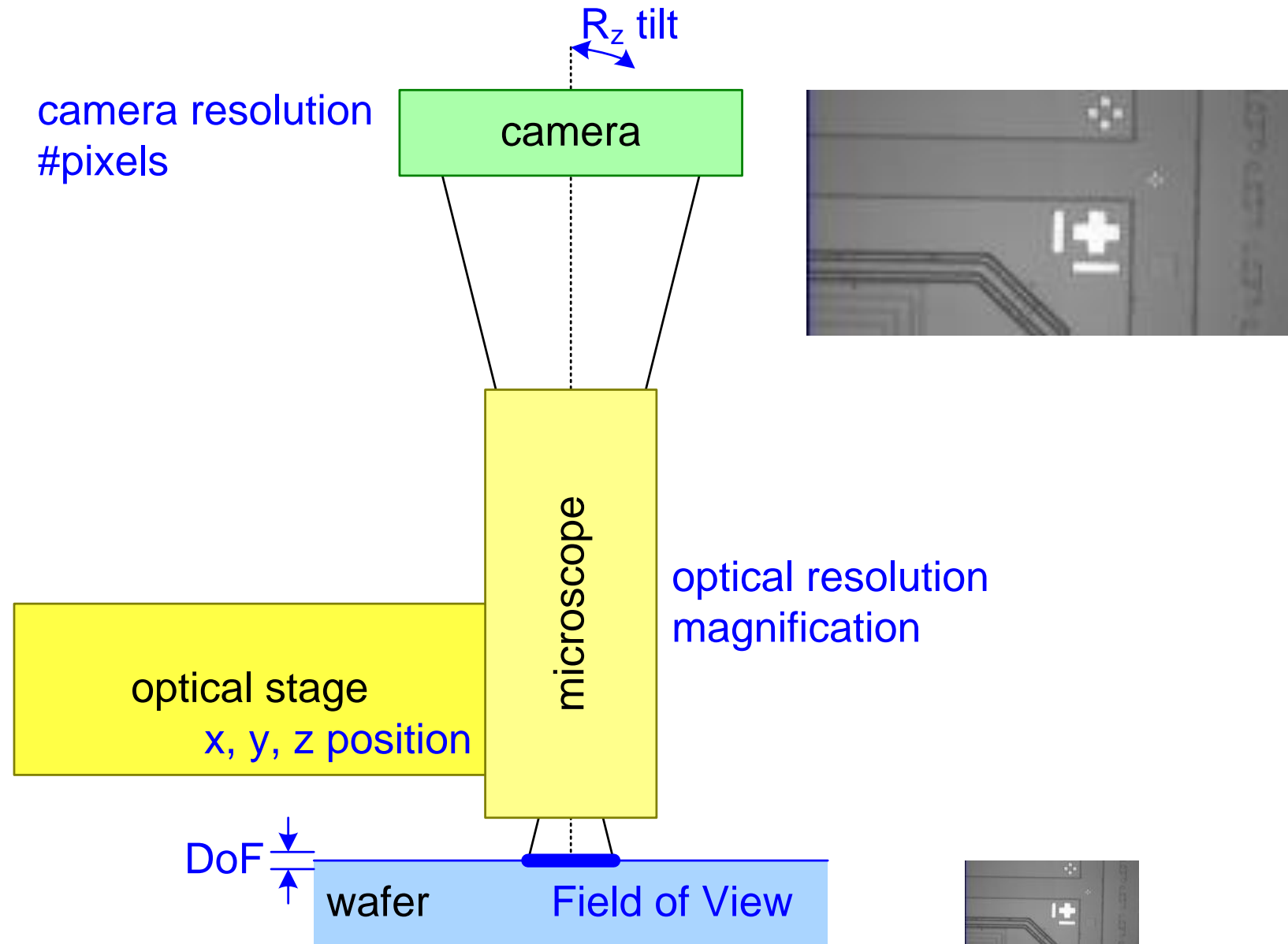
# The Optics Chain



# Optics Chain Block Diagram



# Optics Chain



# What are the Key Functions and KPPs of your Subsystem?

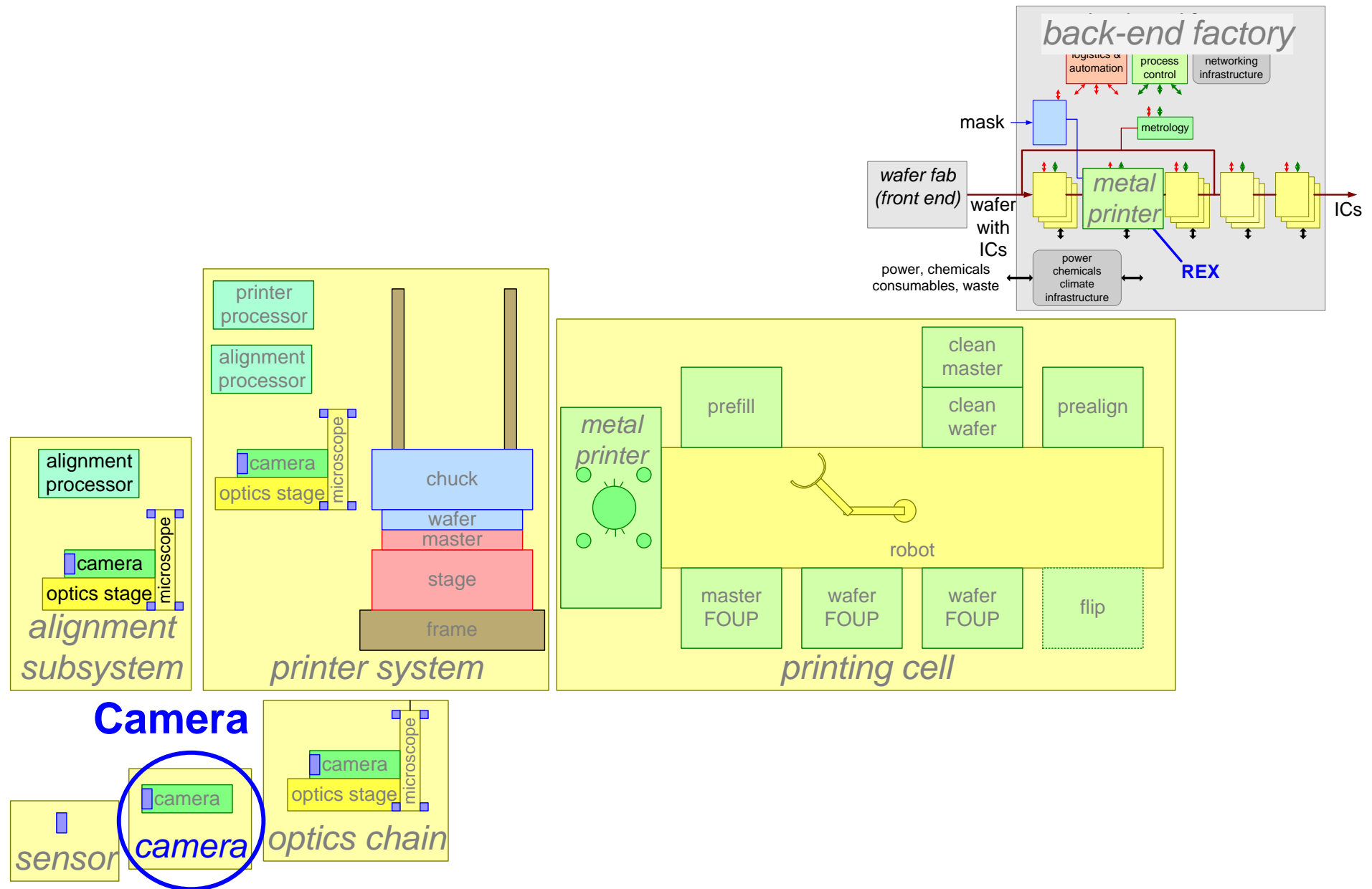
---

- Name 1 subsystem that is essential for your Sol KPPs
- Name 3 key functions of this subsystem essential for your Sol KPPs
- Name 3 KPPs of this subsystem essential for your Sol KPPs
- Quantify these KPPs
- How confident are you about your subsystem answers?

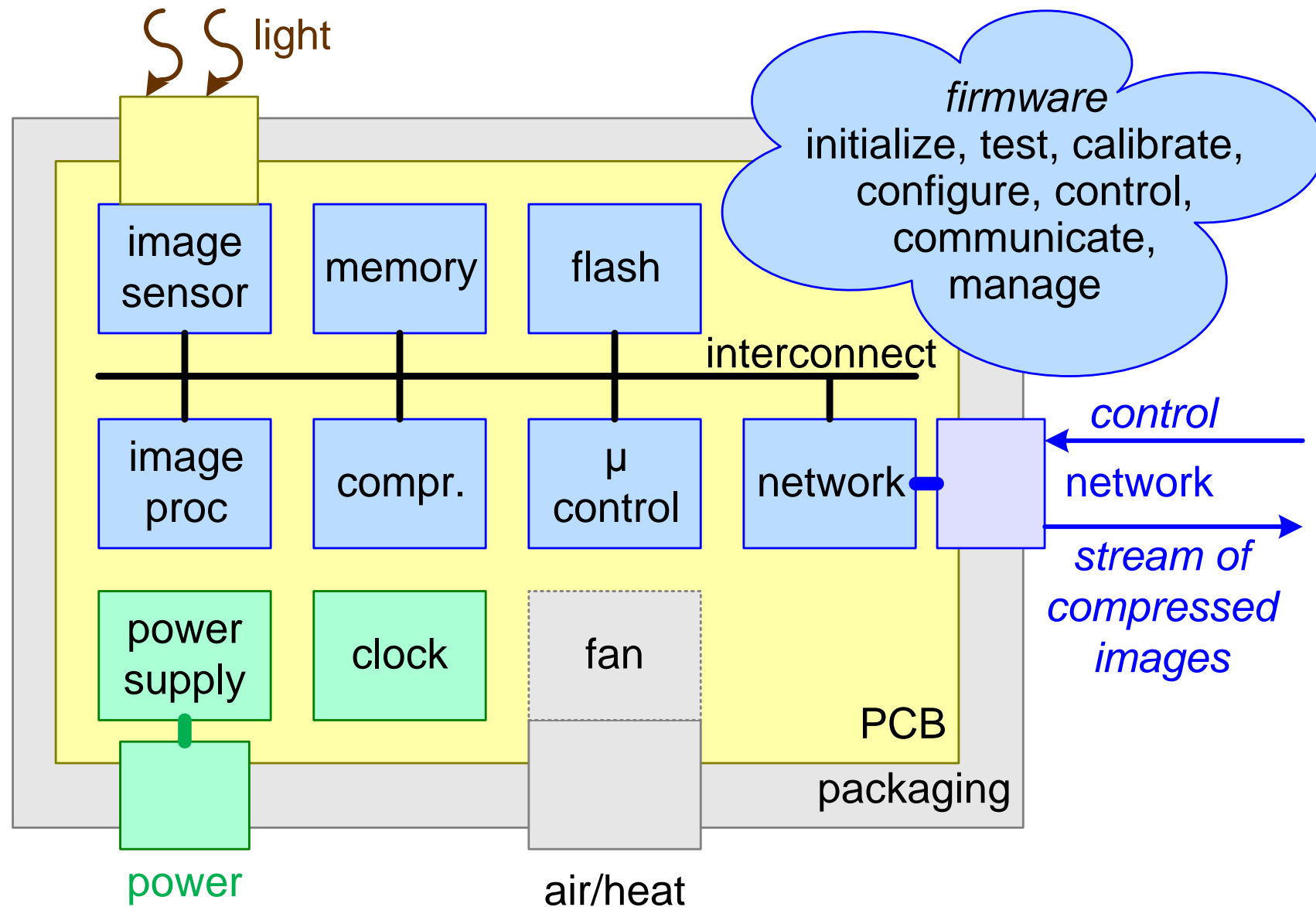
Possible  
*Key Performance Parameters*  
of the optics chain

- position and angle stability
- wafer-to-sensor image quality (resolution, uniformity, color range)
- vertical size
- acquisition performance (frame rate, acquisition time)
- stage performance (speed, stability, reproducibility)
- focus performance
- x, y range
- thermal stability
- cost, weight, size stage+optics

# The Camera



# Camera Block Diagram



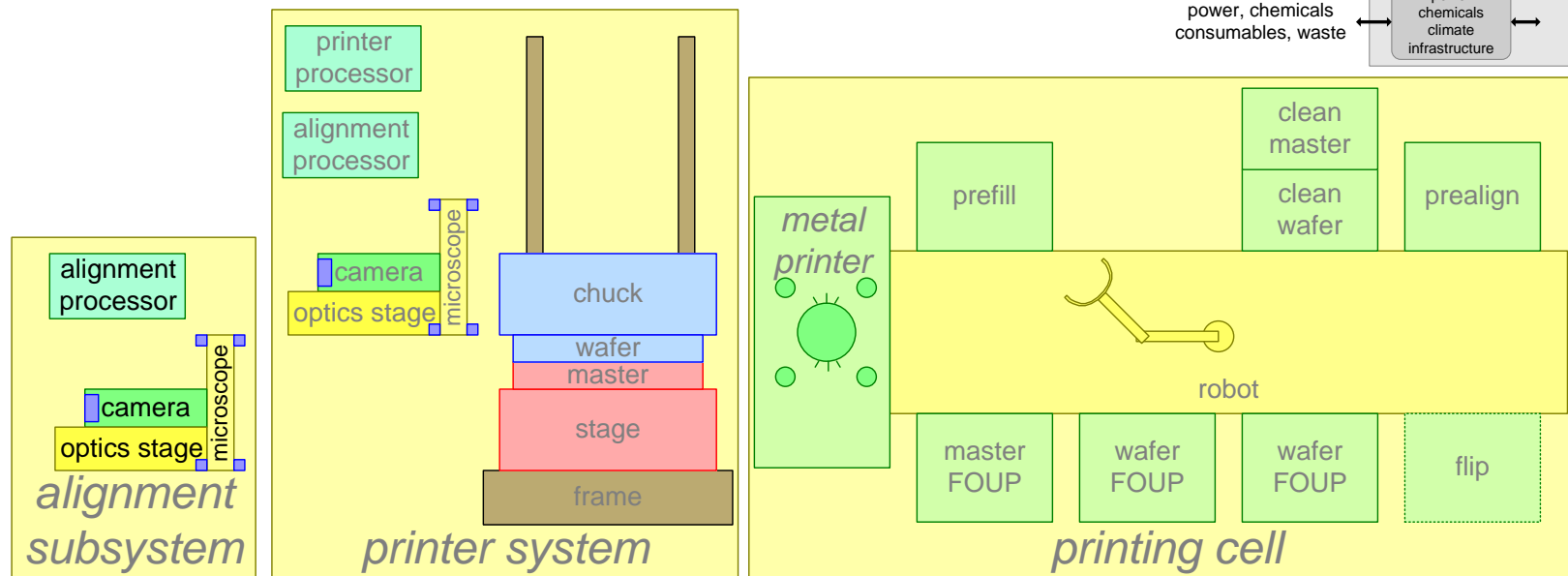
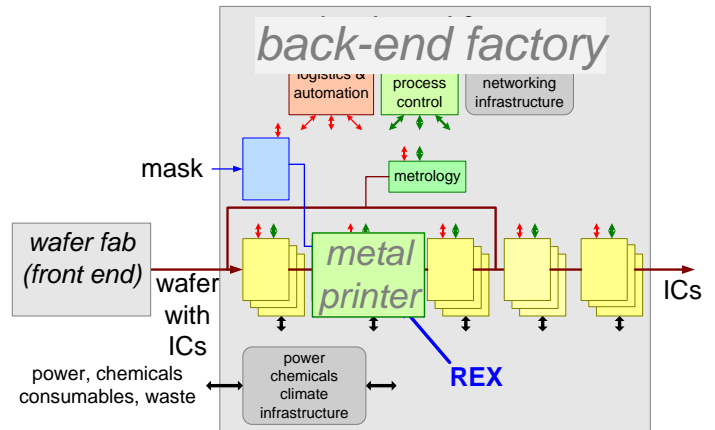
# What are the Key Functions and KPPs of your Subsystem?

- Name 1 subsystem that is essential for your subsystem KPPs
- Name 3 key functions of this subsystem essential for your subsystem KPPs
- Name 3 KPPs of this subsystem essential for your subsystem KPPs
- Quantify these KPPs
- How confident are you about your subsystem answers?

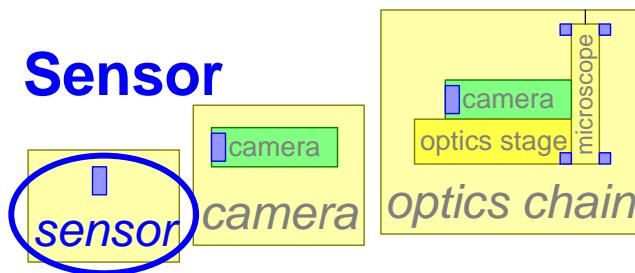
Possible  
*Key Performance Parameters*  
of the camera

- image quality (resolution, uniformity, color range)
- acquisition performance (frame rate, acquisition time)
- camera size, weight
- camera energy consumption, thermal stability
- camera cost price
- storage capacity
- compression rate and quality
- communication performance

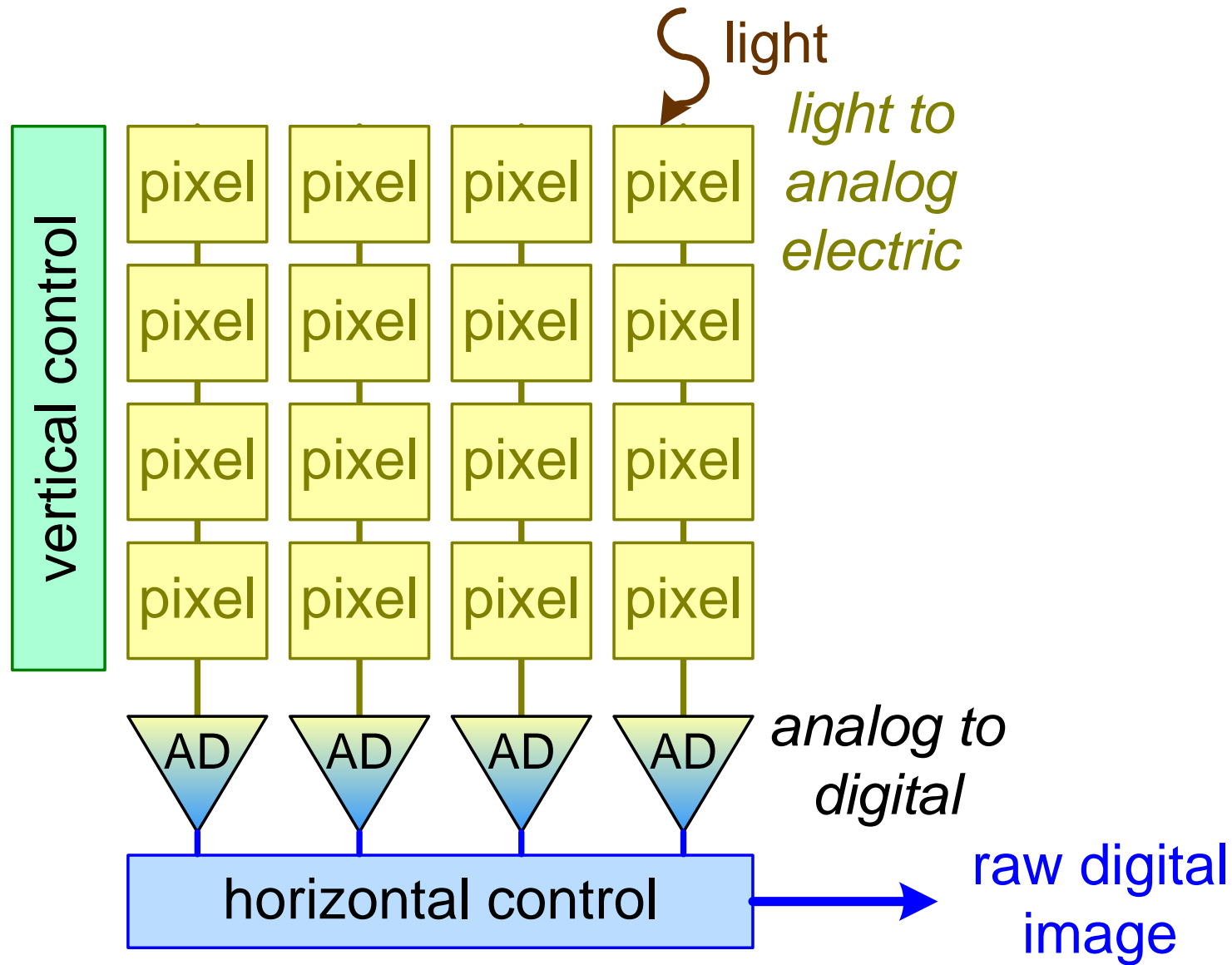
# The Sensor



## Sensor



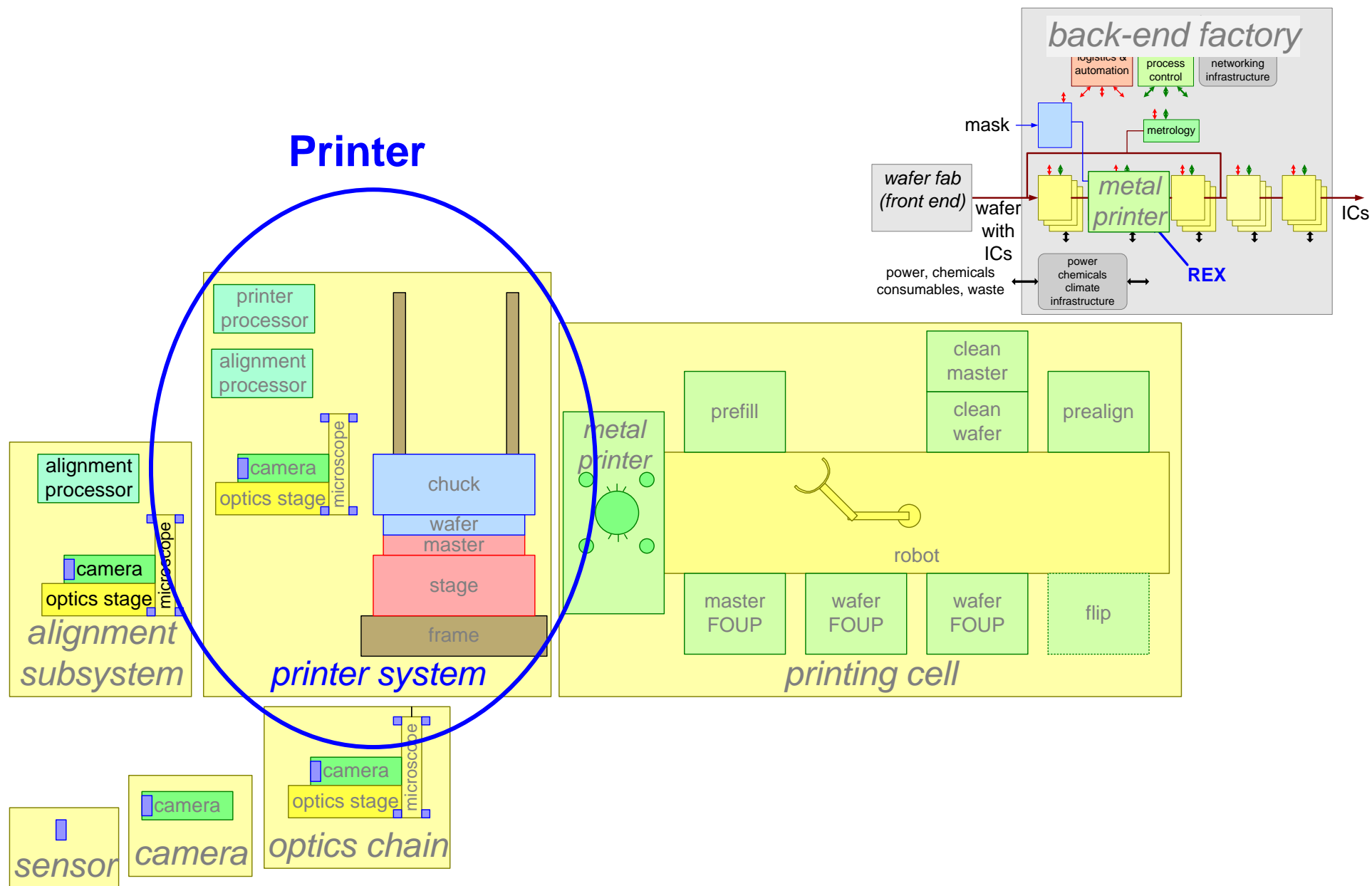
# Sensor Block Diagram



## Possible *Key Performance Parameters* of the sensor

- spatial resolution
- contrast resolution
- frame rate
- image acquisition time
- image uniformity
- sensor size
- energy consumption
- cost price
- color range
- sensitivity

# The Printer



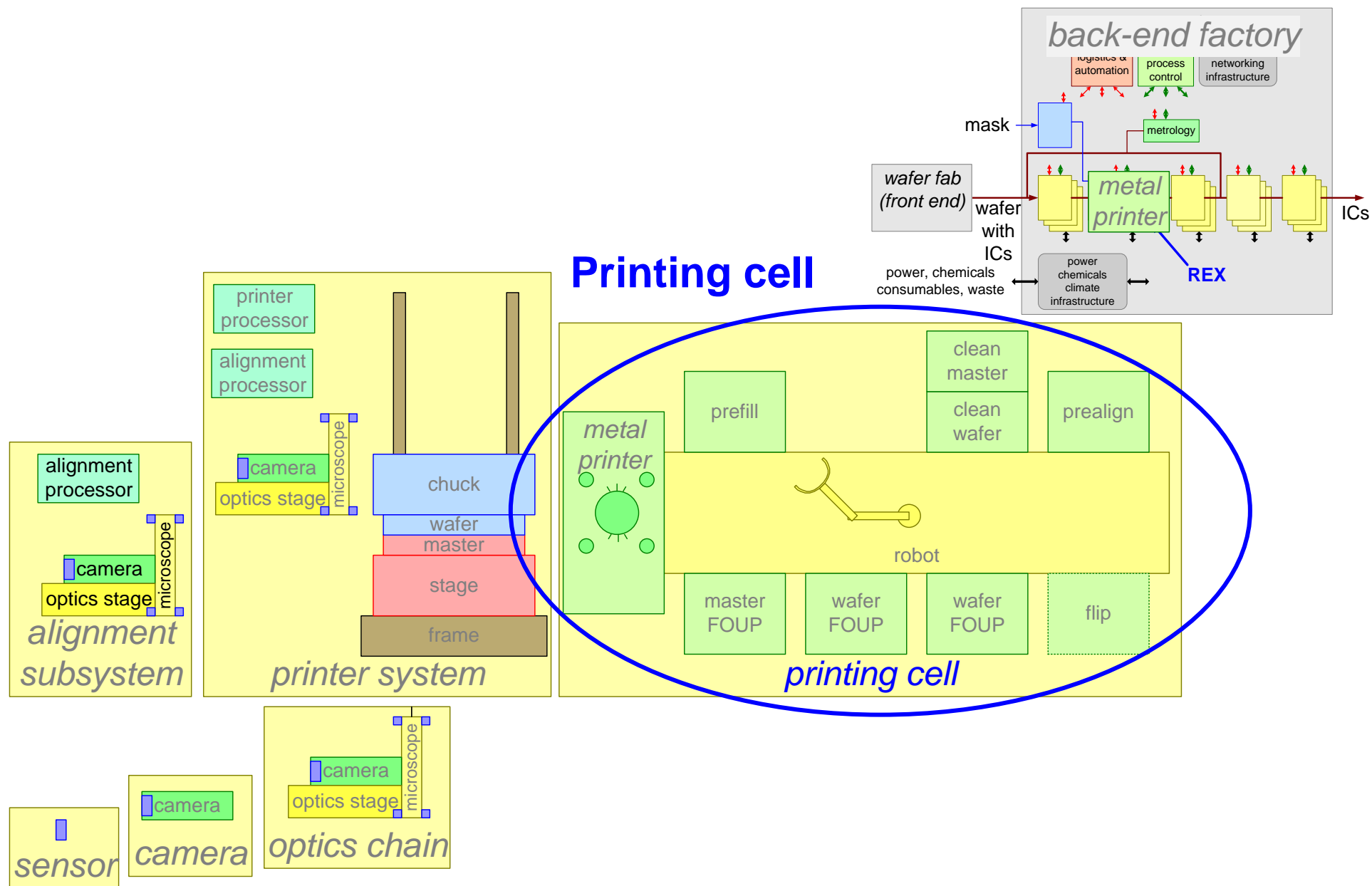
# What are the Key Functions and KPPs of your Supersystem?

- Name a supersystem that is needs your system KPPs
- Name 3 key functions of this supersystem needing your system KPPs
- Name 3 KPPs of this supersystem needing your system KPPs
- Quantify these KPPs
- How confident are you about your supersystem answers?

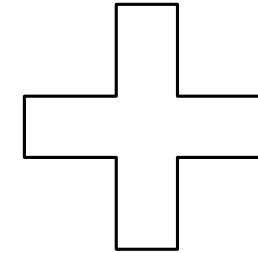
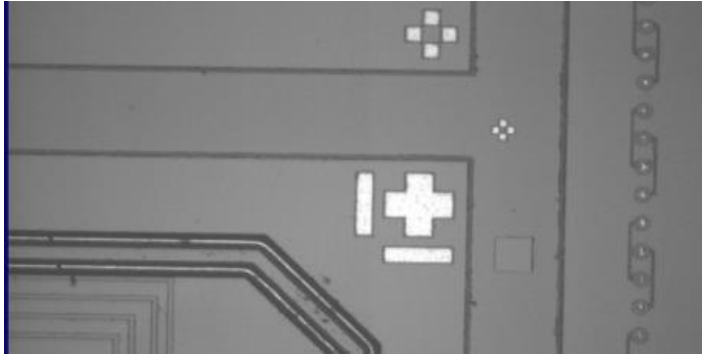
Possible  
*Key Performance Parameters*  
of the printer system

- print quality (pattern resolution, cross section control)
- overlay (=positioning accuracy)
- throughput
- reliability (uptime, high MTBF)
- robustness for markers, patterns, wafers, temperature
- integral costs (system cost, operational costs)
- consumables and waste
- fab interoperability (wafers and information)
- footprint

# The Printer



# How Process can Influence Alignment



Context: process influence on alignment

what if little contrast



what if slow transition



what if wafer surface height varies

what if shadows

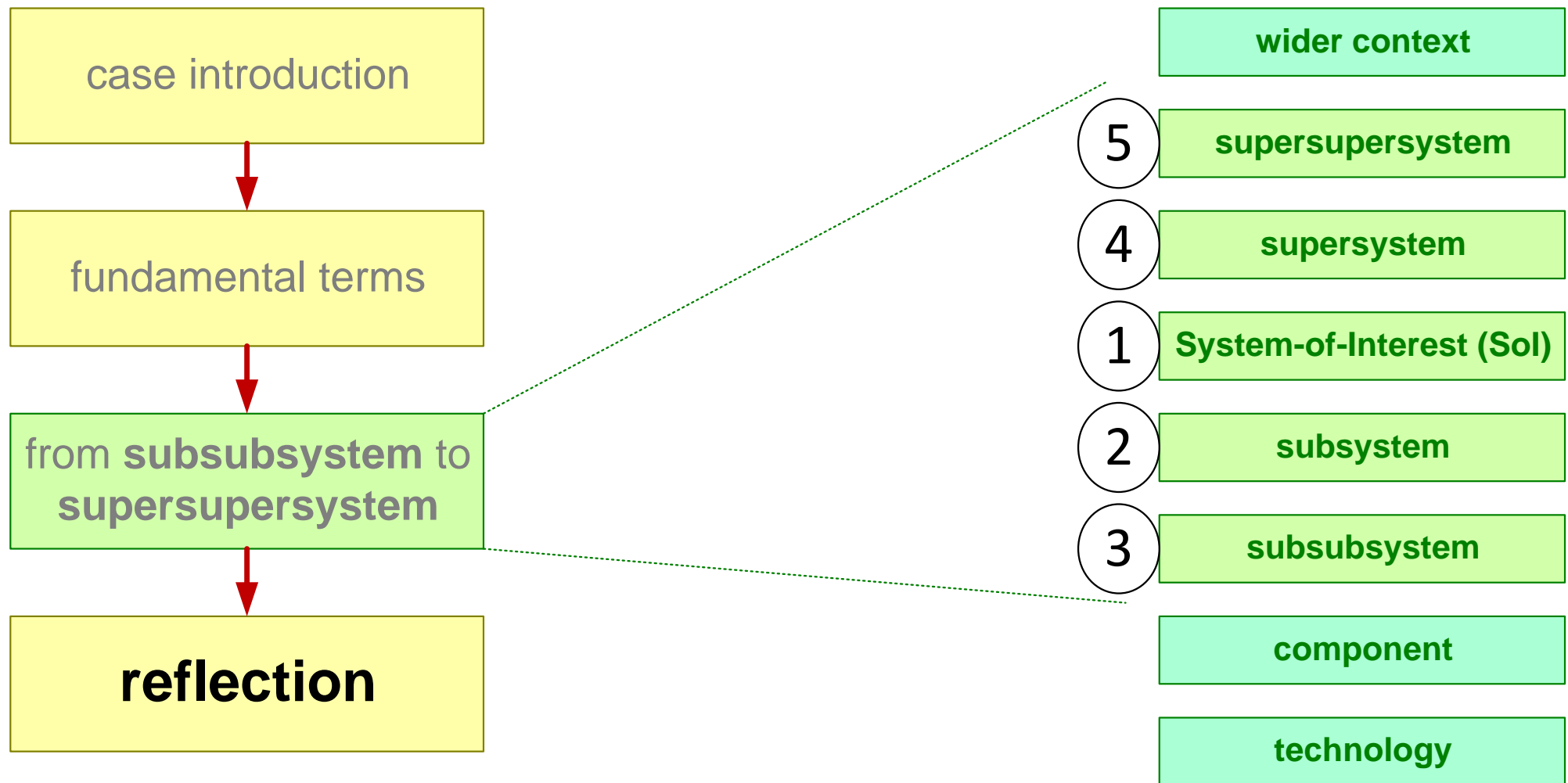


what if marker is damaged

# What are the Key Functions and KPPs of your Supersupersystem

- Name a supersupersystem that is needs your supersystem KPPs
- Name 3 key functions of this supersupersystem needing your supersystem KPPs
- Name 3 KPPs of this supersupersystem needing your supersystem KPPs
- Quantify these KPPs
- How confident are you about your supersupersystem answers?

# Time for Reflection



# Part of the Design Space

	<i>benefits</i>	<i>disadvantages</i>
high resolution	accurate dx, dy	long acq time long transfer time long calculation time high energy consumption
large FoV	easy to find markers	long acq time long transfer time high energy consumption
red light	visibility marker	low optical resolution
blue light	high optical resolution	poor visibility marker
continuous on	thermal steady state	requires continuous cooling

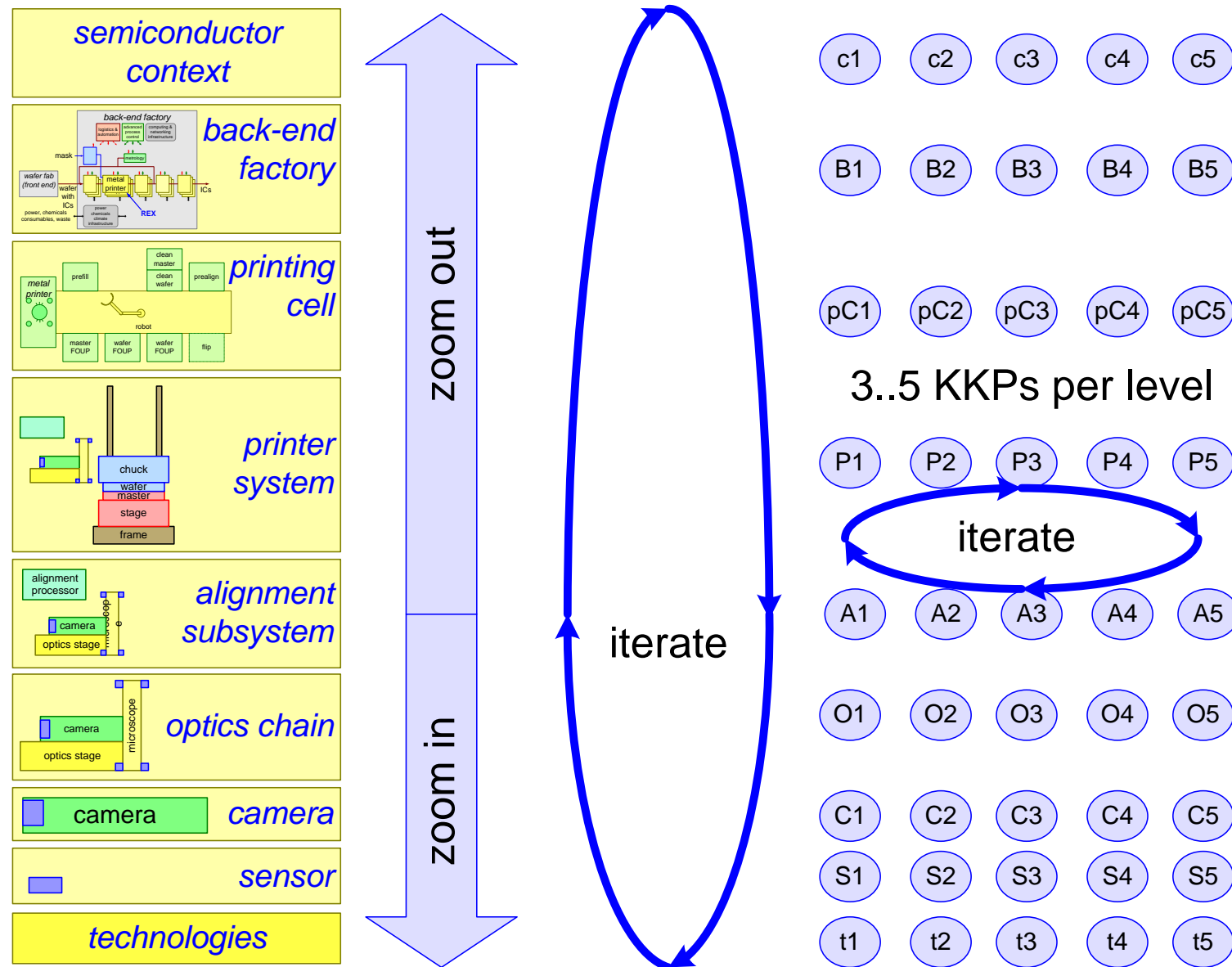
  

```

graph LR
    sensor[sensor] -- raw image --> camera[camera]
    camera -- compressed stream --> alignment_processor[alignment processor]
  
```

accuracy ↔ alignment time  
 ↔  
 thermal stability ↔

# Architecting: 8 Orders Zoom in-out



# What are your Reflections?

---

- What is your **personal range**?
- Where do you want to know more?
- What are the **benefits** of this seminar for you?
- What are the **concerns** of this seminar for you? E.g., what would you like to change?